

# GLOBAL SEMICONDUCTOR PACKAGING MATERIALS MARKET FORECAST 2017-2025

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## Abstracts

### KEY FINDINGS

The global semiconductor packaging materials market was valued \$21.34 billion in 2016 and is anticipated to reach \$32.81 billion by 2025, growing at an estimated CAGR of 4.96% over the forecast period of 2017-2025. The market growth is mainly driven by a growing demand for smart devices, widespread use of semiconductor IC'S in IOT field and the several technological advancements in semiconductor technology.

### MARKET INSIGHTS

The global semiconductor packaging material market segmentation is chiefly done on the basis of packaging technology and the materials used. The packaging technology includes Grid Array (GA) Packages, Small Outline (SO) Packages, Flat No-Leads Packages, Dual In-Line Package (DIP), Quad Flat Packages (QFP), and Other Technologies. The packaging material types are sub-divided into lead frames, organic substrates, bonding wires, ceramic package, encapsulation resins, DIE attach materials and solder balls.

### REGIONAL INSIGHTS

Region-wise, the Global Semiconductor Packaging Materials Market has been segmented into seven major regions, i.e., Taiwan, China, South Korea, United States, Japan, Europe and Rest of world. The Chinese market dominated the global semiconductor market in the year 2016, closely followed by Taiwan. Over the years, the semiconductor packaging material market has witnessed considerable progress in the Chinese market due to several contributory factors like high production capacity and

easy availability of inexpensive raw materials.

## **COMPETITIVE INSIGHTS**

Applied Materials, Amkor Technology, Asm Pacific Technology (ASMPT), Carsem Inc, BASF Se, Dupont, Henkel, Hitachi Chemical, Evergreen Semiconductor Materials, Honeywell, Kyocera, Jiangsu Changjiang Electronics Technology Co Ltd, LG Innotek, Platform Specialty Products Corporation, Mitsui High-Tec Inc, Sumitomo Chemical Co. Ltd, Tanaka Holdings Co. Ltd, Taiwan Semiconductor Manufacturing Company Ltd, Toppan Printing, Xiamen Yonghong Electronics and Toray Industries Corporation are some of the noted companies in the global semiconductor packaging market.

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2. APPLIED MATERIALS
3. ASM PACIFIC TECHNOLOGY (ASMPT)
4. BASF SE
5. CARSEM, INC
6. DUPONT
7. HENKEL
8. EVERGREEN SEMICONDUCTOR MATERIALS
9. HITACHI CHEMICAL
10. HONEYWELL
11. JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD.
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